

## **AMENDMENTS TO THE CLAIMS**

Claims 1-6 (Cancelled).

7. (Previously Presented) A substrate processing apparatus, comprising:  
a loading/unloading area for carrying in and out a substrate;  
a cleaning area for cleaning the substrate; and  
a plating area for plating the substrate,  
wherein the cleaning area is provided with a pre-cleaning unit including a vessel housing a first treatment liquid spraying section for cleaning the substrate before plating in the plating area by bringing a first treatment liquid into contact with the substrate, a lid member for closing an opening of the vessel after the substrate held in a substrate holding device is moved to above the opening, and a second treatment liquid spraying section mounted on the lid member for cleaning the substrate by bringing a second treatment liquid into contact with the substrate while the opening of the vessel is closed with the lid member.

Claim 8 (Cancelled).

9. (Previously Presented) A substrate processing apparatus, comprising:  
a loading/unloading area for carrying in and out a substrate;  
a cleaning area for cleaning the substrate; and  
a plating area for plating the substrate,  
wherein the plating area is provided with a first pretreatment unit and a second pretreatment unit, each unit including a vessel housing a first treatment liquid spraying section for pretreating the substrate before plating by bringing a first treatment liquid into contact with the substrate, a lid member for closing an opening of the vessel after the substrate held in a substrate holding device is moved to above the opening, and a second treatment liquid spraying section mounted on the lid member for cleaning the substrate by bringing a second treatment

liquid into contact with the substrate while the opening of the vessel is closed with the lid member.

10. (Previously Presented) A substrate processing apparatus, comprising:  
a loading/unloading area for carrying in and out a substrate;  
a cleaning area for cleaning the substrate; and  
a plating area for plating the substrate,

wherein the plating area is provided with a plating unit including a processing tank for holding a plating solution, a lid member for closing an opening of the processing tank after the substrate held in a substrate holding device is moved to above the opening, and a treatment liquid spraying section mounted on the lid member for cleaning the substrate by bringing a cleaning liquid into contact with the substrate while the opening of the processing tank is closed with the lid member.

Claims 11-17 (Cancelled).

18. (Previously Presented) A substrate processing apparatus, comprising:  
a loading/unloading area for carrying in and out a substrate;  
a cleaning area for cleaning the substrate; and  
a plating area for plating the substrate,  
wherein the plating area is provided with a plurality of plating units, each plating unit including a processing tank for holding a plating solution, a lid member for closing an opening of the processing tank after the substrate held in a substrate holding device is moved to above the opening, and a treatment liquid spraying section mounted on the lid member for cleaning the substrate by bringing a cleaning liquid into contact with the substrate while the opening of the processing tank is closed with the lid member.

Claims 19-32 (Cancelled).

33. (Previously Presented) A substrate processing apparatus, comprising:

a loading/unloading area for carrying in and out a substrate;

a cleaning area for cleaning the substrate; and

a plating area for plating the substrate,

wherein the plating area is provided with a pretreatment unit for pretreating the substrate before plating by bringing a treatment liquid into contact with the substrate, said pretreatment unit, including;

a processing tank for holding a plating solution,

a lid member for closing an opening of the processing tank after the substrate held in a substrate holding head is moved to above the opening, and

a treatment liquid spraying section mounted on the lid member for spraying a cleaning liquid onto the substrate to clean the substrate while the opening of the processing tank is closed with the lid member, said substrate fixing head being provided with a tilting mechanism.

Claims 34-75 (Cancelled).